

3724



Attorney Docket No.: VLSI-2759.CPA

THE UNITED STATES PATENT AND TRADEMARK OFFICE

I hereby certify that this transmittal of the below described document is being deposited with the United States Postal Service in an envelope bearing First Class Postage and addressed to the U.S. Patent and Trademark Office, Washington, D.C., 20231, on the below date of deposit.			
Date of Deposit:	01/04/02	Name of Person Making the Deposit:	Julie Williams
		Signature of the Person Making the Deposit:	<i>Julie Williams</i>

In re Application of: Charles F. Drill and Miling Weling

Serial No.: 08/824,633

Examiner: Rachuba, M.

Filed: 03/27/97

Art Unit: 3724

For: A CUSTOMIZED POLISHING PAD FOR SELECTIVE PROCESS PERFORMANCE DURING CHEMICAL MECHANICAL POLISHING

Assistant Commissioner for Patents
Washington, D.C. 20231

AMENDMENT AND RESPONSE TRANSMITTAL

1. Transmitted herewith is an amendment for this application

☒ Transmitted herewith is a response to an office action for the above identified patent application.
(7 sheets)

Transmitted herewith are sheets of substitute formal drawings.

Other:

2. Applicant is other than a small entity

Extension of Term

3. The proceedings herein are for a patent application and the provisions of 37 C.F.R. 1.136 apply.

(a) ☐ Applicant petitions for an extension of time under 37 C.F.R. 1.136
(fees: 37 C.F.R. 1.17(a)-(d) for the total number of months checked below:)

Extension	Fee
<input type="checkbox"/> one month	\$110.00
<input type="checkbox"/> two months	\$400.00
<input type="checkbox"/> three months	\$920.00
<input type="checkbox"/> four months	\$1,960.00

Fee \$

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If an additional extension of time is required, please consider this a petition therefor.

(b) ☒ Applicant believes that no extension of term is required. However, this conditional petition is being made to provide for the possibility that applicant has inadvertently overlooked the need for a petition for extension of time.

Fee Calculation

4. The fee for claims (37 C.F.R. 1.16(b)-(d)) has been calculated as shown below:

(for other than a small entity)					
Fee Items	Claims Remaining After Amendment	Highest Number of Claims Previously Paid For	Present Extra Claims	Fee Rate	Total
Total Claims	21	- 21 =	0	x \$18.00	\$0.00
Independent Claims	5	- 5 =	0	x \$80.00	\$0.00
Multiple Dependent Claim Fee (one or more, first added by this amendment)				\$260.00	\$0.00
Total Fees					\$0.00

PAYMENT OF FEES

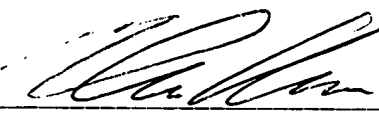
5. The full fee due in connection with this communication is _
provided as follows:
- ☒ The Commissioner is hereby authorized to charge any additional fees associated with this communication or credit any overpayment to Deposit Account No.: 23-0085.
A duplicate copy of this authorization is enclosed.
- ☐ A check in the amount of \$
- ☐ Charge any fees required or credit any overpayments associated with this filing to Deposit Account No.: 23-0085.

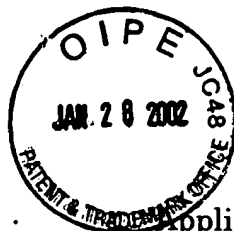
Please direct all correspondence concerning the above-identified application to the following address:

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(408) 938-9060

Respectfully submitted,

Date: 1/4/02

By: 
Glenn D. Barnes
Reg. No. 42,293



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Drill, C. et al.
#22 02/10/02

Applicant : Drill, C. et al.
Serial No. : 08/824,633 Group Art Unit : 3724
Filed : 03/27/97 Examiner : Rachuba, M.
For : A CUSTOMIZED POLISHING PAD FOR SELECTIVE PROCESS
PERFORMANCE DURING CHEMICAL MECHANICAL
POLISHING

AMENDMENT AND RESPONSE

Assistant Commissioner for Patents & Trademarks
Washington, D.C. 20231

Sir:

In response to the Office Action mailed 10/05/01, please amend the
above-referenced Application as follows and consider the following remarks:

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FEB - 4 2002
TC 3100 MAIL ROOM

IN THE CLAIMS

Please amend the claims as follows:

20. (Amended) A process specific polishing pad having a plurality of
regions configured to achieve specific polishing process effects when used in a
wafer polishing machine, the process specific polishing pad comprising:
a polishing pad having an overlying layer, said overlying layer being
uniform and homogenous across a polishing surface of said overlying layer, said
polishing surface adapted to frictionally contact a wafer as said wafer is
polished in said wafer polishing machine; and
said polishing surface having a plurality of regions, each of said plurality
of regions configured to achieve a specific WIW or WID process effect such